



Seiko Seiki STP-200, 300, 400

Technical Specifications

Item		STP-200 series	STP-300 series	STP-400 series
Flange size*1	Inlet port flange	ICF152/VG100/ISO100		ICF203/VG150 /ISO160
	Outlet port flange	KF25		
Pumping speed	N ₂ L/s	270	340	420
	He L/s	220	330	410
	H ₂ L/s	200	310	385
Compression ratio	N ₂	1 × 10 ⁸	>10 ⁸	>10 ⁸
	He	1 × 10 ³	2 × 10 ⁵	2 × 10 ⁵
	H ₂	2 × 10 ²	1 × 10 ⁴	1 × 10 ⁴
Ultimate pressure (after baking) Pa (Torr)	Without anti-corrosion treatment	10 ⁻⁷ (10 ⁻⁹) order	10 ⁻⁸ (10 ⁻¹⁰) order :ICF flange	
	Chemical specific type		10 ⁻⁷ (10 ⁻⁹) order :VG/ISO flange	
Maximum working pressure	Pa (Torr)	1.3 × 10 ⁻² (1 × 10 ⁻⁴)		
Allowable backing pressure	Pa (Torr)	13 (0.1)		
Rated speed	rpm	48,000		
Starting time	min	10		
Stopping time	min	15		
Vibration	μ m O-P	<0.01 (at 48,000 rpm)		
Noise	dB	<50 (at 48,000 rpm)		
Baking temperature	°C	<120		
Lubricating oil		Not necessary		
Installation position		Free		
Cooling method		Natural air cooling (Air cooling: for baking/gas pumping)		
Standard backing pump	L/min	160	240	240
Weight	kg	12		
Dimensions	mm	Φ 180 × H248	Φ 180 × H248	Φ 180 × H218
Ambient temperature range	°C	0 to 40		
Storage temperature range	°C	- 25 to + 55		

The values shown in the table are typical. They are not guaranteed.



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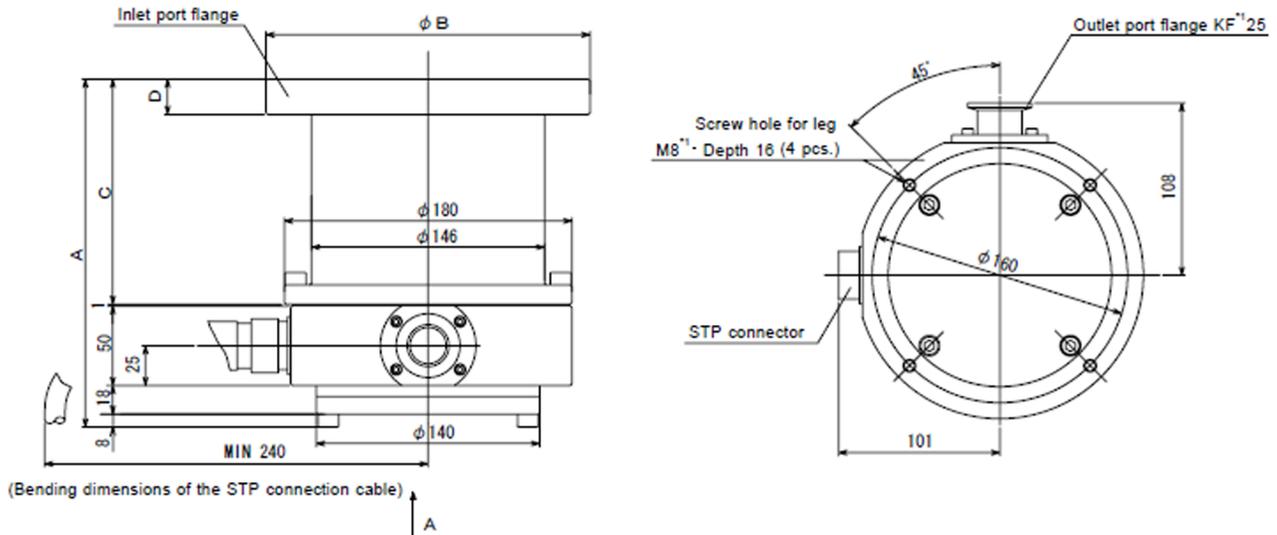
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Seiko Seiki STP-200, 300, 400 Dimensions



Dimensions List (Total Length of the Pump and Flange)

Model	STP-200/300 Series			STP-400 Series		
Flange	ICF*152	VG*100	ISO100	ICF*203	VG*150	ISO160
A	248	248	248	218	218	218
B	152	185	130	203	235	180
C	171	171	171	141	141	141
D	20	14	12	22	12	12

Viewed from arrow A

Unit : mm

*1: JIS

*2: JVIS





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Features & Benefits

- oil free
- low vibration
- high reliability
- maintenance free
- increased life
- advanced controller design
- compact design
- small footprint
- advanced rotor technology
- installation in any orientation

Applications

- plasma etch • ECR etch • film deposition • sputtering • ion implantation source • beam line pumping • MBE • diffusion • photo resist stripping
- crystal / epitaxial growth • wafer inspection • load lock chambers

Recommended controller/backing pump

- controllers: SCU-300
- backing pumps: E2M12